



Materials Declaration Form

IPC	1752	Version	2
Form Type *	Distribute		
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D

* : Required Field


Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2014-06-30
Contact Name *	Refer to "Supplier Comment" section	Contact Title	Refer to "Supplier Comment" section
Contact Phone *	Refer to "Supplier Comment" section	Contact Email *	Refer to "Supplier Comment" section
Authorized Representative *	Giuseppe Vitali Palma	Representative Title	AMS/IPD Materials Declaration Champion)
Representative Phone *	Refer to "Supplier Comment" section	Representative Email *	Refer to "Supplier Comment" section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/internet/com/support/online_tech_support.jsp		

Uncertainty Statement

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Legal Statement			
Supplier Acceptance *	true	Legal Declaration *	Standard
Legal Statement	<p>Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.</p>		

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	XLFP*VJ8LB52	A	SH1A	2014-06-30
Amount	UoM	Unit type	ST ECOPACK Grade	
1901.51	mg	Each	ECOPACK® 2	

Manufacturing information					
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles	 life.augmented		
NAC	NAC	NAC			
bulk Solder Termination	Terminal Plating	Terminal Base Alloy			Comment
Not Applicable ; if coating is used o	Tin (Sn), matte	Copper Alloy			

Package Designator	Size	Nbr of instances	Shape	
SIP	10.2X9.2X4.5	3	Through-hole	
Comment	Package: TO 220 ISO FULL PACK IN LINE			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
Product(s) meets EU RoHS requirement without any exemptions	false
Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
Product(s) meets EU RoHS requirements by application of the selected exemption(s)	true
Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Product(s) is obsolete, no information is available	false
Product(s) is unknown, no information is available	false
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

QueryList : REACH-16th December 2013				
Query				Response
The product does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	XLFP*VJ8LB52					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
die (s)	Other inorganic materials	23.478	mg	supplier	die	Silicon (Si)	7440-21-3		22.547	mg	960346	11857
die (s)				supplier	metallization	Aluminium (Al)	7429-90-5		0.448	mg	19082	236
die (s)				supplier	passivation	Silicon Nitride (SiN)	68034-42-4		0.106	mg	4515	56
die (s)				supplier	passivation	Silicon Oxide(SiO2)	7631-86-9		0.158	mg	6730	83
die (s)				supplier	back side metallization	Titanium (Ti)	7440-32-6		0.011	mg	469	6
die (s)				supplier	back side metallization	Silver (Ag)	7440-22-4		0.054	mg	2300	28
die (s)				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.154	mg	6559	81
Leadframe	Copper & its alloys	648.082	mg	supplier	alloy	Copper (Cu)	7440-50-8		647.227	mg	998679	340375
Leadframe				supplier	alloy	Iron (Fe)	7439-89-6		0.648	mg	1000	341
Leadframe				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		0.194	mg	299	102
Leadframe				supplier	metallization	Nickel (Ni)	7440-02-0		0.013	mg	20	7
Die attach	Other Organic Materials	14.782	mg	JIG R	Soft solder	Lead (Pb)	7439-92-1	7a-Lead in high me	14.116	mg	954945	7424
Die attach				supplier	Soft solder	Silver (Ag)	7440-22-4		0.37	mg	25030	195
Die attach				supplier	Soft solder	Tin (Sn)	7440-31-5		0.296	mg	20024	156
Bonding wire	Other inorganic materials	1.994	mg	supplier	wire	Aluminium (Al)	7429-90-5		1.993	mg	999498	1048
Bonding wire				supplier	wire	Magnesium (Mg)	7429-90-5		0.001	mg	502	1
encapsulation	Other Organic Materials	1207.307	mg	supplier	mold compound	Silica, vitreous	60676-86-0		90.548	mg	75000	47619
encapsulation				supplier	mold compound	Quartz	14808-60-7		845.115	mg	700000	444444
encapsulation				supplier	mold compound	Epoxy resin	Proprietary		169.023	mg	140000	88889
encapsulation				supplier	mold compound	phenol resin	Proprietary		84.511	mg	70000	44444
encapsulation				supplier	mold compound	carbon black	1333-86-4		6.037	mg	5000	3175
encapsulation				supplier	mold compound	metal hydroxide	Proprietary		12.073	mg	10000	6349
connections coating	Solder	5.866	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		5.866	mg	1000000	3085